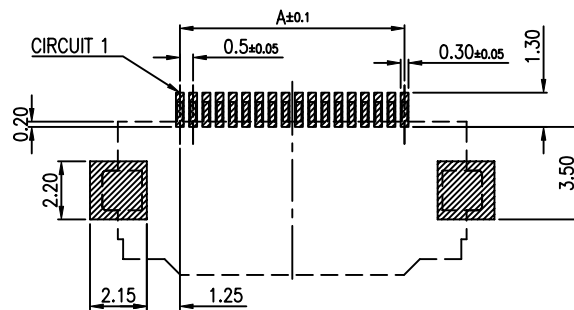
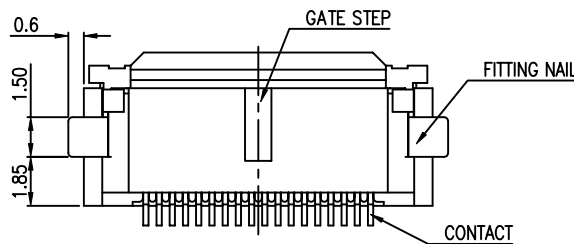
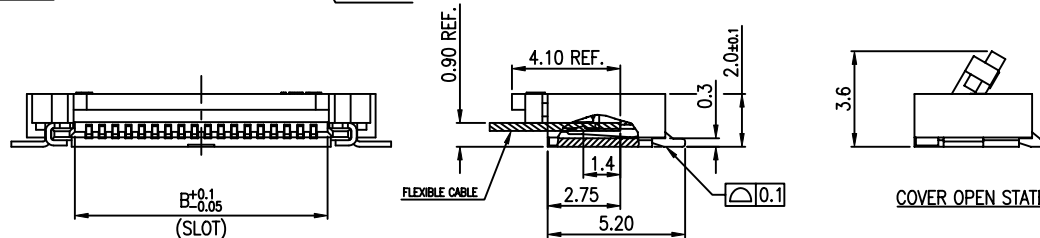
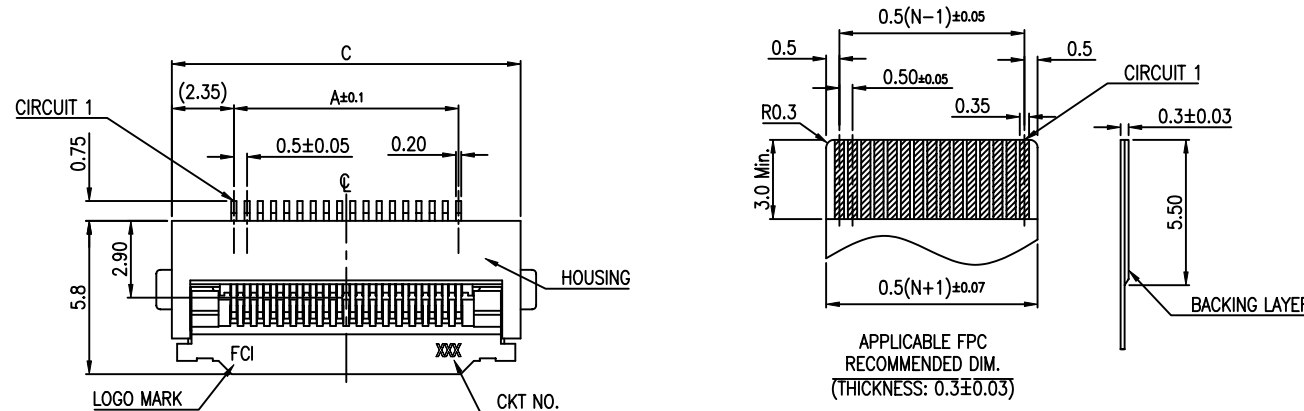




RECOMMENDED PC BOARD PATTERN DIM.(REF.)

NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL 94V-0
 - 1.2 ACTUATOR: THERMOPLASTIC, HIGH TEMP., UL 94V-0
 - 1.3 CONTACT: COPPER ALLOY
 - 1.4 FITTING NAIL: COPPER ALLOY
2. FINISH:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - CONTACT AREA AND SOLDER TAIL: GOLD FLASH OVERALL
 - FITTING NAIL:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - MATTE TIN PLATING 100u" MIN. OVERALL
3. REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP. FOR 10 SECONDS MAX.
4. SPEC. PLS. REFER TO GS-12-578.
5. PACKAGE PLS. REFER TO GS-14-1330.
6. PART NUMBER DESCRIPTION

10089708-XXX 0 1 X LF

NO. OF CONTACTS(CKT)

PACKING
0: TAPE & REEL

LEAD FREE

COLOR

X: HOUSING ACTUATOR
0: NATURAL BLACK

PLATING

1: GOLD FLASH OVERALL

CKT	DIM.A	DIM.B	DIM.C
004	1.50	2.56	6.2
006	2.50	3.56	7.2
008	3.50	4.56	8.2
010	4.50	5.56	9.2
012	5.50	6.56	10.2
014	6.50	7.56	11.2
016	7.50	8.56	12.2
026	12.50	13.56	17.2
030	14.50	15.56	19.2

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	FCI			
ltr	ecn no	dr	date	linear	.X ± 0.25		www.fciconnect.com			
A	T08-1182	WL	11/06/08	linear	.XX ± 0.15	projection	title			
B	T08-1196	WL	12/10/08		.XXX ± 0.10		0.5mm FPC CONN. SMT			
C	T09-1005	WL	01/20/09	angles	0° ± 2°		R/A B/C TYPE			
D	T09-1132	WL	10/15/09	dr	LEIF SHEN	08-06-18	product family FPC			
E	T10-0046	WL	04/15/10	enr	DENNIS GOH	08-08-08	code			
F	T10-0108	WL	07/02/10	chr	DENNIS GOH	08-08-08	size dwg no			
				appd	JOEY NG	08-08-08	A4			
sheet index		revision sheet		F	1		10089708			
							SNG			
							sheet 1 of 1			